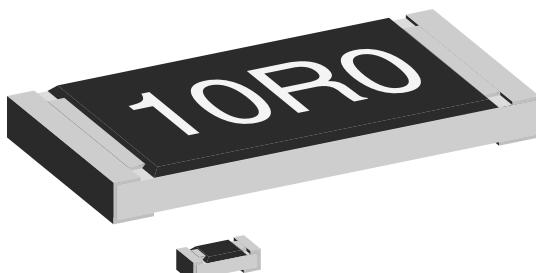


## Lead (Pb)-free Thick Film, Rectangular Commodity Chip Resistors



### FEATURES

- High volume product suitable for commercial applications
- Stability ( $\Delta R/R \leq 1\%$  for 1000 h at  $70^\circ\text{C}$ )
- Lead (Pb)-free solder contacts on Ni barrier layer
- Metal glaze on ceramic
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



STANDARD ELECTRICAL SPECIFICATIONS								
MODEL	CASE SIZE INCH	CASE SIZE METRIC	POWER RATING $P_{70^\circ\text{C}}$ W	LIMITING ELEMENT VOLTAGE MAX. V $\geq$	TEMPERATURE COEFFICIENT ppm/K	TOLERANCE %	RESISTANCE RANGE $\Omega$	E-SERIES
CRCW0402...C	0402	RR 1005M	0.063	50	$\pm 100$	$\pm 1$	1R0 to 10M	E24; E96
					$\pm 200$	$\pm 5$	1R0 to 10M	E24
Zero-Ohm-Resistor: $R_{\max.} = 20 \text{ m}\Omega$ , $I_{\max.}$ at $70^\circ\text{C} = 1.5 \text{ A}$								
CRCW0603...C	0603	RR 1608M	0.10	75	$\pm 100$	$\pm 1$	1R0 to 10M	E24; E96
					$\pm 200$	$\pm 5$	1R0 to 10M	E24
Zero-Ohm-Resistor: $R_{\max.} = 20 \text{ m}\Omega$ , $I_{\max.}$ at $70^\circ\text{C} = 2.0 \text{ A}$								
CRCW0805...C	0805	RR 2012M	0.125	150	$\pm 100$	$\pm 1$	1R0 to 10M	E24; E96
					$\pm 200$	$\pm 5$	1R0 to 10M	E24
Zero-Ohm-Resistor: $R_{\max.} = 20 \text{ m}\Omega$ , $I_{\max.}$ at $70^\circ\text{C} = 2.5 \text{ A}$								
CRCW1206...C	1206	RR 3216M	0.25	200	$\pm 100$	$\pm 1$	1R0 to 10M	E24; E96
					$\pm 200$	$\pm 5$	1R0 to 10M	E24
Zero-Ohm-Resistor: $R_{\max.} = 20 \text{ m}\Omega$ , $I_{\max.}$ at $70^\circ\text{C} = 3.5 \text{ A}$								

#### Notes

- These resistors do not feature a limited lifetime when operated within the permissible limits. However, resistance value drift increasing over operating time may result in exceeding a limit acceptable to the specific application, thereby establishing a functional lifetime
- Power rating depends on the max. temperature at the solder point, the component placement density and the substrate material

TECHNICAL SPECIFICATIONS					
PARAMETER	UNIT	CRCW0402...C	CRCW0603...C	CRCW0805...C	CRCW1206...C
Rated dissipation at $70^\circ\text{C}$ <sup>(1)</sup>	W	0.063	0.10	0.125	0.25
Limiting element voltage $U_{\max.}$ AC/DC	V	50	75	150	200
Insulation voltage $U_{\text{ins.}}$ (1 min)	V	> 75	> 100	> 200	> 300
Insulation resistance	$\Omega$	$> 10^9$			
Category temperature range	$^\circ\text{C}$	- 55 to + 155			
Failure rate	$\text{h}^{-1}$	$0.1 \times 10^{-9}$			
Weight/1000 pieces	g	0.65	2	5.5	10

#### Note

- <sup>(1)</sup> The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-circuit board (thermal resistance). The rated dissipation applies only if the permitted film temperature of  $155^\circ\text{C}$  is not exceeded

<b>PART NUMBER AND PRODUCT DESCRIPTION</b>													
<b>PART NUMBER: CRCW0603562RFKECC</b>													
<b>C</b>	<b>R</b>	<b>C</b>	<b>W</b>	<b>0</b>	<b>6</b>	<b>0</b>	<b>3</b>	<b>5</b>	<b>6</b>	<b>2</b>	<b>R</b>	<b>F</b>	<b>K</b>
<b>MODEL/SIZE</b>			<b>VALUE</b>			<b>TOLERANCE</b>			<b>TCR</b>		<b>PACKAGING</b>		<b>SPECIAL</b>
<b>CRCW0402</b>			<b>R = decimal</b>			<b>F = <math>\pm 1.0\%</math></b>			<b>K = <math>\pm 100 \text{ ppm/K}</math></b>		<b>EA, EB,</b>		<b>Up to 2 digits</b>
<b>CRCW0603</b>			<b>K = thousand</b>			<b>J = <math>\pm 5.0\%</math></b>			<b>N = <math>\pm 200 \text{ ppm/K}</math></b>		<b>EC, ED,</b>		<b>C = commodity</b>
<b>CRCW0805</b>			<b>M = million</b>			<b>Z = jumper</b>			<b>O = jumper</b>				
<b>CRCW1206</b>													
<b>PRODUCT DESCRIPTION: CRCW0603-C 100 562R 1 % ET6 E3</b>													
<b>CRCW0603-C</b>	<b>100</b>			<b>562R</b>			<b>1 %</b>			<b>ET6</b>		<b>e3</b>	
<b>MODEL</b>		<b>TCR</b>			<b>RESISTANCE VALUE</b>			<b>TOLERANCE</b>			<b>PACKAGING</b>		<b>LEAD (Pb)-FREE</b>
<b>CRCW0402-C</b>		<b><math>\pm 200 \text{ ppm/K}</math></b>			<b>10R = 10 <math>\Omega</math></b>			<b><math>\pm 5\%</math></b>			<b>ET1, ET5,</b>		<b>e3 = pure tin termination finish</b>
<b>CRCW0603-C</b>		<b><math>\pm 100 \text{ ppm/K}</math></b>			<b>562R = 562 <math>\Omega</math></b>			<b><math>\pm 1\%</math></b>			<b>ET6, ET7,</b>		<b>EF4</b>
<b>CRCW0805-C</b>					<b>10K = 10.0 k<math>\Omega</math></b>								
<b>CRCW1206-C</b>					<b>1M = 1 M<math>\Omega</math></b>								
					<b>OR0 = jumper</b>								

<b>PACKAGING</b>						
<b>TYPE / SIZE</b>	<b>CODE</b>	<b>QUANTITY</b>	<b>PACKAGING STYLE</b>	<b>WIDTH</b>	<b>PITCH</b>	<b>PACKAGING DIMENSIONS</b>
<b>CRCW0402...C</b>	ED = ET7	10 000			2 mm	$\varnothing 180 \text{ mm}/7"$
	EE = EF4	50 000				$\varnothing 330 \text{ mm}/13"$
<b>CRCW0603...C</b>	EA = ET1	5000			4 mm	$\varnothing 180 \text{ mm}/7"$
	EB = ET5	10 000				$\varnothing 254 \text{ mm}/10"$
<b>CRCW0805...C</b>	EC = ET6	20 000			4 mm	$\varnothing 330 \text{ mm}/13"$
	EA = ET1	5000				$\varnothing 180 \text{ mm}/7"$
<b>CRCW1206...C</b>	EB = ET5	10 000			4 mm	$\varnothing 254 \text{ mm}/10"$
	EC = ET6	20 000				$\varnothing 330 \text{ mm}/13"$

Paper tape acc. to IEC 60286-3, Type 1a

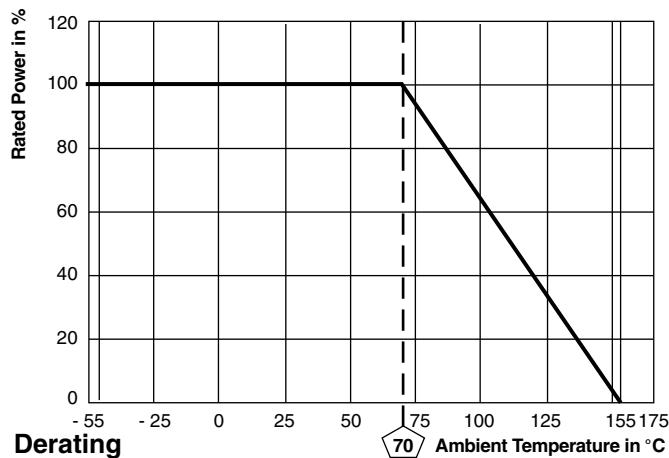
### DIMENSIONS



<b>SIZE</b>	<b>DIMENSIONS (in millimeters)</b>					<b>SOLDER PAD DIMENSIONS<sup>(1)</sup> (in millimeters)</b>			
	<b>INCH</b>	<b>METRIC</b>	<b>L</b>	<b>W</b>	<b>H</b>	<b>T1</b>	<b>T2</b>	<b>a</b>	<b>b</b>
0402	1005	$1.0 \pm 0.10$	$0.5 \pm 0.05$	$0.30 \pm 0.05$	$0.25 \pm 0.10$	$0.2 \pm 0.1$		0.4	0.6
0603	1608	$1.60 \pm 0.10$	$0.80 \pm 0.10$	$0.45 \pm 0.10$	$0.3 \pm 0.2$	$0.3 \pm 0.2$		0.5	0.9
0805	2012	$2.0 \pm 0.10$	$1.25 \pm 0.15$	$0.50 \pm 0.10$	$0.35 \pm 0.15$	$0.35 \pm 0.2$		0.7	1.3
1206	3216	$3.05 \pm 0.10$	$1.55 \pm 0.10$	$0.55^{+0.10}_{-0.05}$	$0.35 \pm 0.15$	$0.45 \pm 0.2$		0.9	1.7

#### Note

(1) The rated dissipation applies only if the permitted film temperature is not exceeded. Furthermore, a high level of ambient temperature or of power dissipation may raise the temperature of the solder joint, hence special solder alloys or board materials maybe required to maintain the reliability of the assembly. Specified power rating above 125 °C requires dedicated heat-sink pads, which depend on board materials. The given solder pad dimensions reflect the considerations for board design and assembly as outlined e.g. in standards IEC 61188-5-x, or in publication IPC-7351. They do not guarantee any supposed thermal properties, particularly as these are also strongly influenced by many other parameters. Still the given solder pad dimensions will be found adequate for most general applications.

**FUNCTIONAL PERFORMANCE**


<b>TEST PROCEDURES AND REQUIREMENTS</b>							
EN 60115-1 CLAUSE	IEC 60068-2 TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE ( $\Delta R$ )			
				STABILITY CLASS 1 OR BETTER	STABILITY CLASS 2 OR BETTER		
Stability for product types:			<b>CRCW...C e3</b>	1 Ω to 10 MΩ	1 Ω to 10 MΩ		
4.5	-	Resistance	(20/- 55/20) °C and (20/125/20) °C	± 1 %	± 5 %		
4.8.4.2	-	Temperature coefficient					
4.13	-	Short time overload	$U = 2.5 \times \sqrt{P_{70} \times R} \leq 2 \times U_{max.}; 5 \text{ s}$	± (2 % $R + 0.1 \Omega$ )			
4.17.5	58 (Td)	Solderability	Pre-aging 4 h at 155 °C, dryheat	Solder bath method; Sn60Pb40 non activated flux; (235 ± 5) °C (2 ± 0.2) s	Good tinning (≥ 95 % covered) no visible damage		
				Solder bath method; Sn96.5Ag3Cu0.5 non activated flux; (245 ± 5) °C (3 ± 0.3) s	Good tinning (≥ 95 % covered) no visible damage		
4.18.2	58 (Td)	Resistance to soldering heat	Solder bath method (260 ± 5) °C; (10 ± 1) s		± (1% $R + 0.05 \Omega$ )		
4.19	14 (Na)	Rapid change of temperature	30 min. at - 55 °C; 30 min. at 125 °C; 5 cycles		± (0.25 % $R + 0.05 \Omega$ )    ± (0.5 % $R + 0.05 \Omega$ )		
4.24	78 (Cab)	Damp heat, steady state	(40 ± 2) °C; 56 days; (93 ± 3) % RH		± (1 % $R + 0.05 \Omega$ )    ± (2 % $R + 0.1 \Omega$ )		
4.36	-	Operation at low temperature	-55 °C, 1 h		± (1 % $R + 0.05 \Omega$ )		
4.25.1	-	Endurance at 70 °C	$U = \sqrt{P_{70} \times R} \leq U_{max.};$ 1.5 h on; 0.5 h off;  70 °C; 1000 h  70 °C; 8000 h	± (1 % $R + 0.05 \Omega$ )  ± (2 % $R + 0.1 \Omega$ )	± (2 % $R + 0.1 \Omega$ )  ± (4 % $R + 0.1 \Omega$ )		
4.25.3	-	Endurance at upper category temperature	155 °C, 1000 h		± (1 % $R + 0.05 \Omega$ )    ± (2 % $R + 0.1 \Omega$ )		

**APPLICABLE SPECIFICATIONS**

- |                 |  |
|-----------------|--|
| • EN 60115-1    | Generic specification                    |
| • EN 140400     | Sectional specification                  |
| • EN 140401-802 | Detail specification                     |
| • IEC 60068-2-X | Variety of environmental test procedures |
| • IEC 60286-3   | Packaging of SMD components              |



## Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.